SIITME2024

IEEE 30th International Symposium for Design and Technology in Electronics Packaging

16th - 19th October 2024, SIBIU, Romania

Conference & Exhibition

Conference Topics

A. Emerging Topics in Advanced Packaging;
B. New Components and Manufacturing Technologies;
C. Printed Electronics, Smart Textiles and Healthcare;
D. Sensors, Actuators and Microsystems;
E. Nanomaterials, Nanoelectronics and Nanotechnology;
F. Embedded Systems, Robotics and Artificial Intelligence;
G. Power Electronics and Thermal Management;
H. Smart Grid and Renewable Energy;
I. Virtual Prototyping and System Validation;
J. Quality Management, Applied Reliability, Characterization and Testing Failure Diagnosis;
K. Corrosion in Electronics;
L. Challenges in Digitalisation and Global Education for Electronics.

Conference Venue

Lucian Blaga University of Sibiu
Faculty of Medicine, *Aula Magna*
📍 *Lucian Blaga* Street nr. 2A, Sibiu

Important Dates

Submission of abstracts:	**30th of June 2024**
Notification of abstract acceptance:	19th of July 2024
Authors and participants registration EARLYBIRD deadline:	1st of September 2024
Submission of camera-ready papers:	22nd of September 2024
Review of camera-ready papers:	6th of October 2024
Submission of modified camera-ready papers (post-review) and copyright forms:	13th of October 2024
Submission of SIITME 2024 presentations and video pitch:	13th of October 2024
Authors and participants registration deadline:	14th of October 2024

Publication of Paper

Accepted papers will be submitted for inclusion into IEEE Xplore subject to meeting IEEE Xplore's scope and quality requirements.

Exhibition

As per our tradition, the Industrial Exhibition will showcase an array of partners and sponsors from across the industry, presenting their expertise in cutting-edge technologies, products and insights into the future of the industrial sector, while at the same time offering a unique networking opportunity.

3rd Summit of IEEE EPS & NTC SBCs

On the 15th of October, one day before the SIITME conference, the 3rd Summit of IEEE EPS & NTC Student Branch Chapters will take place as a co-location event.

EPS
IEEE NANO
IEEE HU&RO EPS&NTC JOINT CHAPTER

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Association for Promoting Electronics Technology

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